LATTICE SEMICONDUCTOR

Device Material Content

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Package: **484 caBGA**
Total Device Weight **0.911** **Grams**

Package Code: **BG484**
Products: LCMXO3-9400

Assembly: ASEK
Size (mm): 19 x 19
Lead pitch (mm): 0.8
MSL: 3
Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.49%	0.0136						Die size: 4968 x 5092 um
			1.49%	0.0136	Silicon chip	7440-21-3	100.00%	
Mold Compound	52.67%	0.4798						Mold Compound: KE-G1250AHT
			46.09%	0.4198	Silica	60676-86-0	87.50%	
			3.42%	0.0312	Epoxy resin	-	6.50%	
			2.90%	0.0264	Phenol Resin	-	5.50%	
			0.26%	0.0024	Carbon Black	1333-86-4	0.50%	
D/A Epoxy	0.21%	0.0019						Die attach epoxy: Henkel 2100A
			0.17%	0.00151	Silver	7440-22-4	80.00%	
			0.04%	0.00038	Esters & resins	-	20.00%	
Wire	0.85%	0.0077						CuPdAu+
			0.821%	0.00748	Copper (Cu)	7440-50-8	96.55%	
			0.026%	0.00024	Palladium (Pd)	7440-05-3	3.10%	
			0.003%	0.00003	Gold (Au)	7440-57-5	0.35%	
Solder Balls	18.49%	0.1684						SAC305
			17.84%	0.1625	Tin (Sn)	7440-31-5	96.50%	
			0.55%	0.0051	Silver (Ag)	7440-22-4	3.00%	
			0.09%	0.0008	Copper (Cu)	7440-50-8	0.50%	
Substrate	16.53%	0.1506						BT Resin CCL-HL832NX-A
			5.29%	0.0482	BT Resins	-	32.00%	
			11.24%	0.1024	Glass fiber	65997-17-3	68.00%	
Foil	5.82%	0.0530						
			4.77%	0.0434	Copper	7440-50-8	82.00%	
			0.88%	0.0080	Nickel	7440-02-0	15.10%	
			0.17%	0.0015	Gold	7440-57-5	2.91%	
Solder Mask	3.94%	0.0359						Solder mask PSR4000 AUS 320
			0.93%	0.0084	Solvent naphtha (petroleum)	64742-94-5	23.52%	
			1.51%	0.0137	Phosphinoxide derivative	-	38.20%	
			0.58%	0.0053	Talc (containing no asbestiform fibers)	14807-96-6	14.70%	
			0.58%	0.0053	Epoxy Resin	85954-11-6	14.70%	
			0.35%	0.0032	Barium Sulfate	7727-43-7	8.88%	

Br/Cl/Sb
Pb lead-free
RoHS

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